

## PRODUCT SPECIFICATION FOR INFORMATION

PRELIMINARY SPECIFICATION

**Product Name : LC Band Pass Filter**

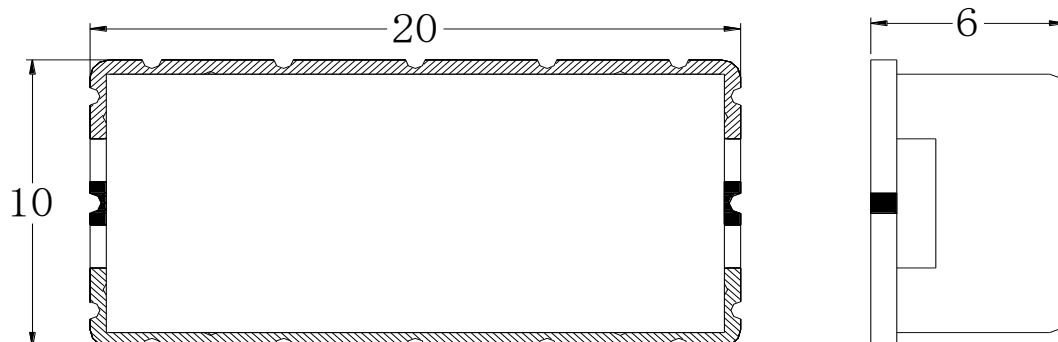
**Part No : MBP-C1750-500MS-A-R0**

### ■ History List

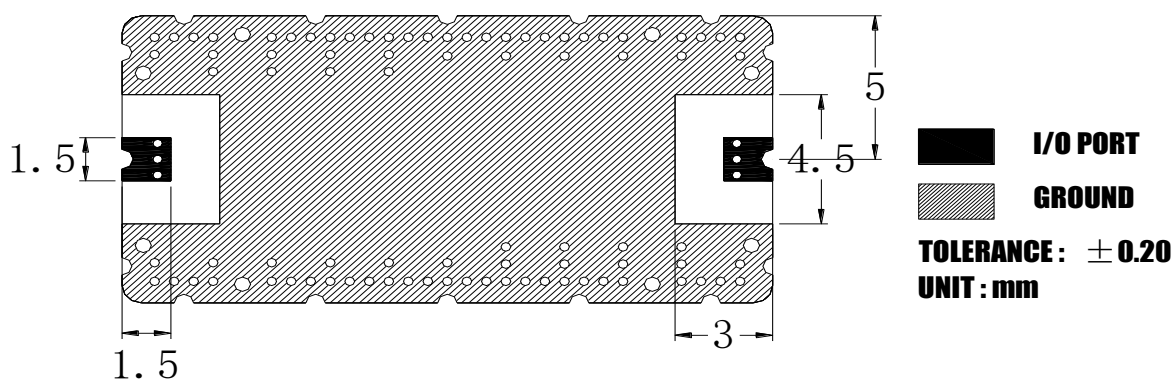
| No. | Rev. No. | Description | Date       | Author       | Final Approver |
|-----|----------|-------------|------------|--------------|----------------|
| 1   | R0       | Draft       | 2023.02.06 | Jeffrey Jeon | Michael Jeon   |
| 2   |          |             |            |              |                |
| 3   |          |             |            |              |                |
| 4   |          |             |            |              |                |
| 5   |          |             |            |              |                |
| 6   |          |             |            |              |                |

## ■ Mechanical Drawing

TOP VIEW



BOTTOM VIEW

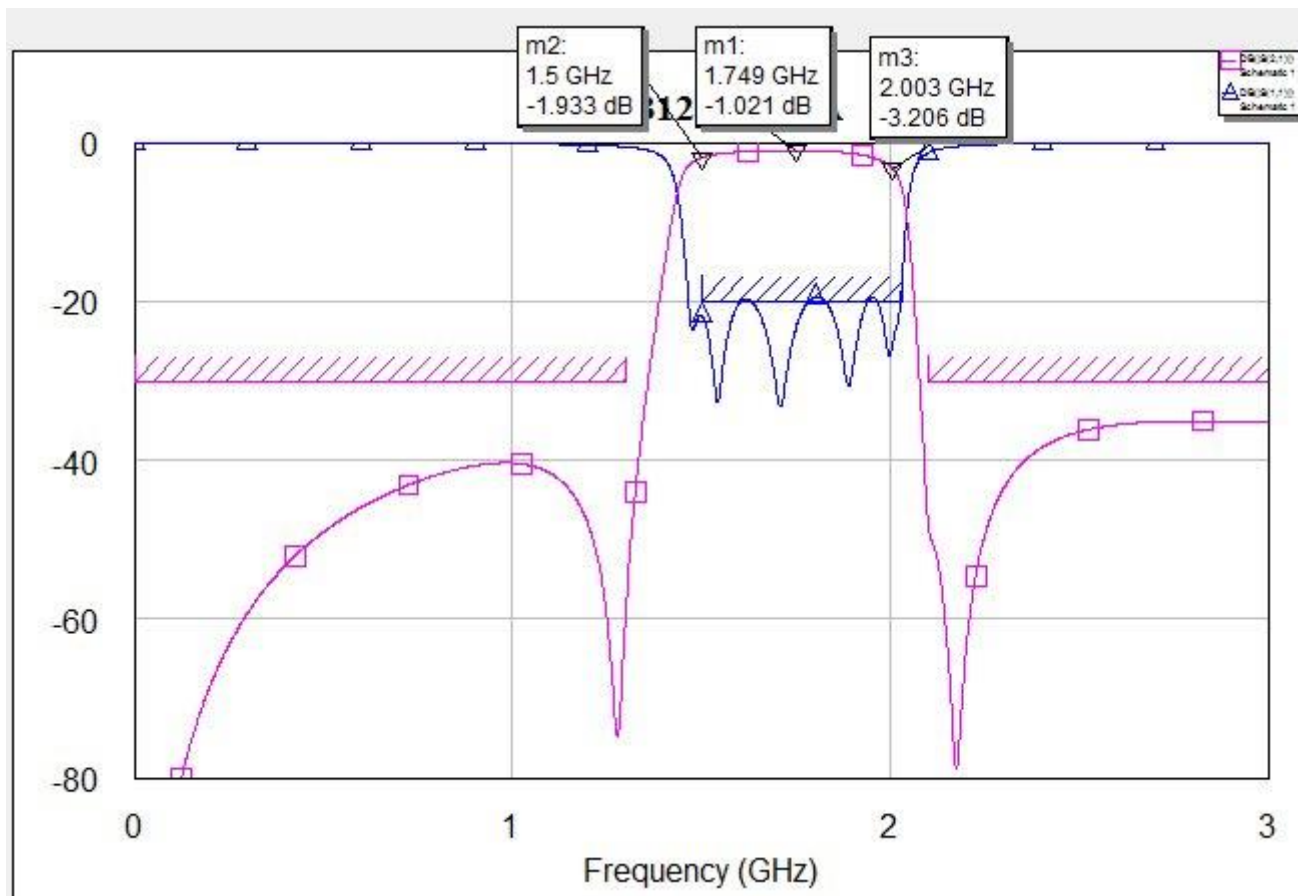


## ■ Electrical Specification

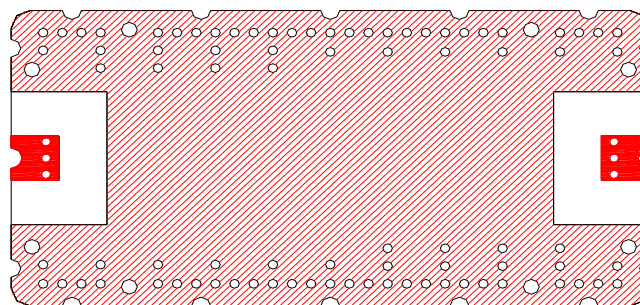
| Parameter           | Specification                                        | Remark |
|---------------------|------------------------------------------------------|--------|
| 1. Center Frequency | 1750MHz                                              |        |
| 2. Frequency Range  | Fo ±250[1500 ~ 2000]MHz                              |        |
| 3. Insertion Loss   | 3.0dB Max.                                           |        |
| 4. Passband Ripple  | 1.0dB Max.                                           |        |
| 5. VSWR             | 1.5 : 1 Max.                                         |        |
| 6. Rejection        | 30dB Min @ DC ~ 1300MHz<br>30dB Min @ 2100 ~ 3000MHz |        |
| 7. Power Handling   | 1W Max                                               |        |
| 8. Impedance        | 50Ω                                                  |        |
| 9. Size             | 20.0 X 10.0 X 6.0mm                                  |        |

※It is subjected to change with prior notice.

## ■ Simulation Curve



## ■ Recommended PCB Land Pattern



**I/O PORT**



**GROUND**

※Recommended using the solder pate of 183°C melting temperature